

**N-Ch and P-Ch Fast Switching MOSFETs**
**General Description**

The UD4302 is the highest performance trench N-ch and P-ch MOSFETs with extreme high cell density , which provide excellent RDSON and gate charge for most of the synchronous buck converter applications .

The UD4302 meet the RoHS and Green Product requirement 100% EAS guaranteed with full function reliability approved.

**Features**

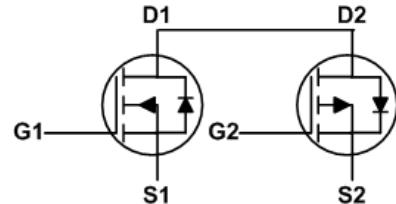
- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

**Product Summary**

BVDSS	RDSON	ID
40V	13.5mΩ	39A
-40V	32mΩ	-27A

**Applications**

- High Frequency Point-of-Load Synchronous Buck Converter for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- CCFL Back-light Inverter

**TO252 Pin Configuration**

**Absolute Maximum Ratings**

Symbol	Parameter	Rating		Units
		N-Ch	P-Ch	
$V_{DS}$	Drain-Source Voltage	40	-40	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	$\pm 20$	V
$I_D @ T_c = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	39	-27	A
$I_D @ T_c = 100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	30	-21	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	80	-54	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	69	76	mJ
$I_{AS}$	Avalanche Current	25	-28.6	A
$P_D @ T_c = 25^\circ C$	Total Power Dissipation <sup>4</sup>	35	35	W
$T_{STG}$	Storage Temperature Range	-55 to 150	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	-55 to 150	°C

**Thermal Data**

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>	---	62	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	---	3.6	°C/W

**N-Ch and P-Ch Fast Switching MOSFETs**
**N-Channel Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$ , $I_D=250\mu\text{A}$	40	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	BVDSS Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_D=1\text{mA}$	---	0.034	---	$\text{V}/^\circ\text{C}$
$R_{DS(\text{ON})}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{GS}=10\text{V}$ , $I_D=20\text{A}$	---	11	13.5	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}$ , $I_D=10\text{A}$	---	15	18.5	
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$ , $I_D=250\mu\text{A}$	1.0	1.5	2.5	V
$\Delta V_{GS(\text{th})}$	$V_{GS(\text{th})}$ Temperature Coefficient		---	-5.64	---	$\text{mV}/^\circ\text{C}$
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=32\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\mu\text{A}$
		$V_{DS}=32\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=55^\circ\text{C}$	---	---	5	
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 20\text{V}$ , $V_{DS}=0\text{V}$	---	---	$\pm 100$	nA
$g_{fs}$	Forward Transconductance	$V_{DS}=5\text{V}$ , $I_D=20\text{A}$	---	35.9	---	S
$R_g$	Gate Resistance	$V_{DS}=0\text{V}$ , $V_{GS}=0\text{V}$ , $f=1\text{MHz}$	---	2.1	---	$\Omega$
$Q_g$	Total Gate Charge (4.5V)	$V_{DS}=20\text{V}$ , $V_{GS}=4.5\text{V}$ , $I_D=12\text{A}$	---	10.7	---	nC
$Q_{gs}$	Gate-Source Charge		---	3.3	---	
$Q_{gd}$	Gate-Drain Charge		---	4.2	---	
$T_{d(on)}$	Turn-On Delay Time	$V_{DD}=12\text{V}$ , $V_{GS}=10\text{V}$ , $R_G=3.3\Omega$	---	8.6	---	ns
$T_r$	Rise Time		---	3.4	---	
$T_{d(off)}$	Turn-Off Delay Time		---	24.8	---	
$T_f$	Fall Time		---	2.2	---	
$C_{iss}$	Input Capacitance	$V_{DS}=15\text{V}$ , $V_{GS}=0\text{V}$ , $f=1\text{MHz}$	---	1314	---	pF
$C_{oss}$	Output Capacitance		---	120	---	
$C_{rss}$	Reverse Transfer Capacitance		---	88	---	

**Guaranteed Avalanche Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
EAS	Single Pulse Avalanche Energy <sup>5</sup>	$V_{DD}=25\text{V}$ , $L=0.1\text{mH}$ , $I_{AS}=20\text{A}$	45	---	---	mJ

**Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current <sup>1,6</sup>	$V_G=V_D=0\text{V}$ , Force Current	---	---	39	A
$I_{SM}$	Pulsed Source Current <sup>2,6</sup>		---	---	80	A
$V_{SD}$	Diode Forward Voltage <sup>2</sup>	$V_{GS}=0\text{V}$ , $I_s=1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	1.2	V

Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $V_{DD}=25\text{V}$ , $V_{GS}=10\text{V}$ , $L=0.1\text{mH}$ , $I_{AS}=25\text{A}$
- 4.The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 5.The Min. value is 100% EAS tested guarantee.
- 6.The data is theoretically the same as  $I_D$  and  $I_{DM}$  , in real applications , should be limited by total power dissipation.

**N-Ch and P-Ch Fast Switching MOSFETs**
**P-Channel Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_D=-250\mu\text{A}$	-40	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	$\text{BV}_{\text{DSS}}$ Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_D=-1\text{mA}$	---	-0.02	---	$\text{V}/^\circ\text{C}$
$R_{\text{DS}(\text{ON})}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{\text{GS}}=-10\text{V}$ , $I_D=-8\text{A}$	---	25	32	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V}$ , $I_D=-4\text{A}$	---	38	46	
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_D=-250\mu\text{A}$	-1.0	-1.6	-2.5	V
$\Delta V_{\text{GS}(\text{th})}$	$V_{\text{GS}(\text{th})}$ Temperature Coefficient		---	3.72	---	$\text{mV}/^\circ\text{C}$
$I_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=-32\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\text{uA}$
		$V_{\text{DS}}=-32\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=55^\circ\text{C}$	---	---	5	
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=-5\text{V}$ , $I_D=-8\text{A}$	---	10.7	---	S
$Q_g$	Total Gate Charge (-4.5V)	$V_{\text{DS}}=-15\text{V}$ , $V_{\text{GS}}=-4.5\text{V}$ , $I_D=-1\text{A}$	---	11.5	---	nC
$Q_{\text{gs}}$	Gate-Source Charge		---	3.5	---	
$Q_{\text{gd}}$	Gate-Drain Charge		---	3.3	---	
$T_{\text{d}(\text{on})}$	Turn-On Delay Time	$V_{\text{DD}}=-15\text{V}$ , $V_{\text{GS}}=-10\text{V}$ , $R_G=3.3\Omega$ , $I_D=-1\text{A}$	---	22	---	ns
$T_r$	Rise Time		---	15.7	---	
$T_{\text{d}(\text{off})}$	Turn-Off Delay Time		---	59	---	
$T_f$	Fall Time		---	5.5	---	
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=-15\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	1415	---	pF
$C_{\text{oss}}$	Output Capacitance		---	134	---	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	102	---	

**Guaranteed Avalanche Characteristics**

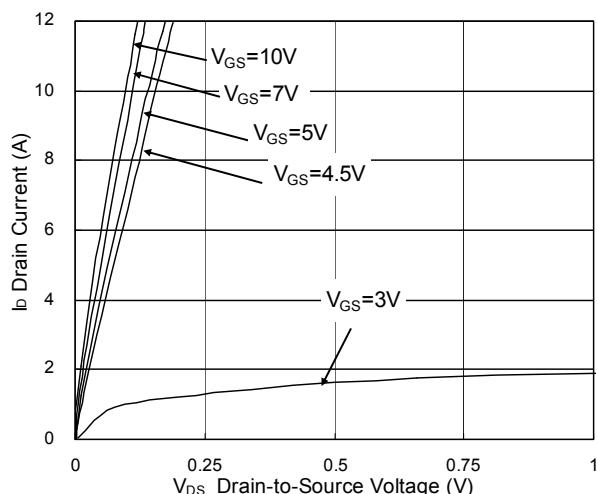
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
EAS	Single Pulse Avalanche Energy <sup>5</sup>	$V_{\text{DD}}=-25\text{V}$ , $L=0.1\text{mH}$ , $I_{\text{AS}}=-20\text{A}$	37	---	---	mJ

**Diode Characteristics**

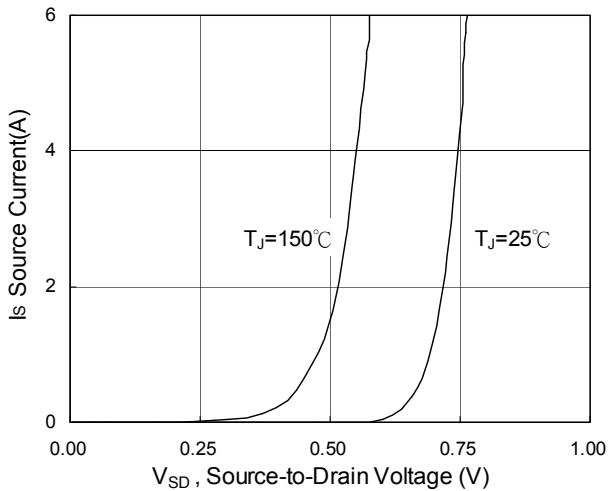
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current <sup>1,6</sup>	$V_G=V_D=0\text{V}$ , Force Current	---	---	-27	A
$I_{\text{SM}}$	Pulsed Source Current <sup>2,6</sup>		---	---	-54	A
$V_{\text{SD}}$	Diode Forward Voltage <sup>2</sup>	$V_{\text{GS}}=0\text{V}$ , $I_s=-1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	-1.2	V

Note :

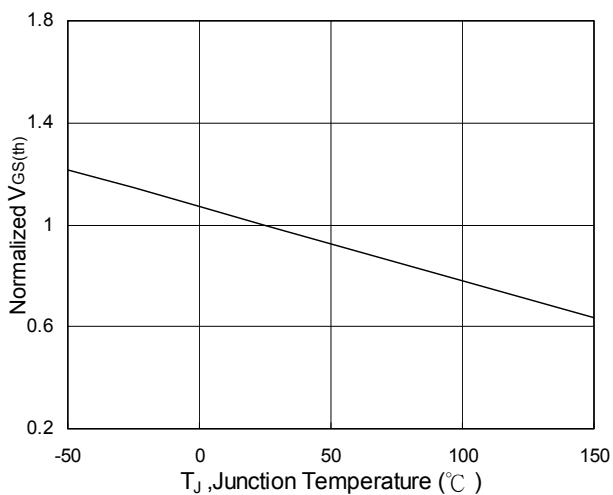
- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $V_{\text{DD}}=-25\text{V}$ , $V_{\text{GS}}=-10\text{V}$ , $L=0.1\text{mH}$ , $I_{\text{AS}}=-28.6\text{A}$
- 4.The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 5.The Min. value is 100% EAS tested guarantee.
- 6.The data is theoretically the same as  $I_D$  and  $I_{\text{DM}}$  , in real applications , should be limited by total power dissipation.



**Fig.1 Typical Output Characteristics**

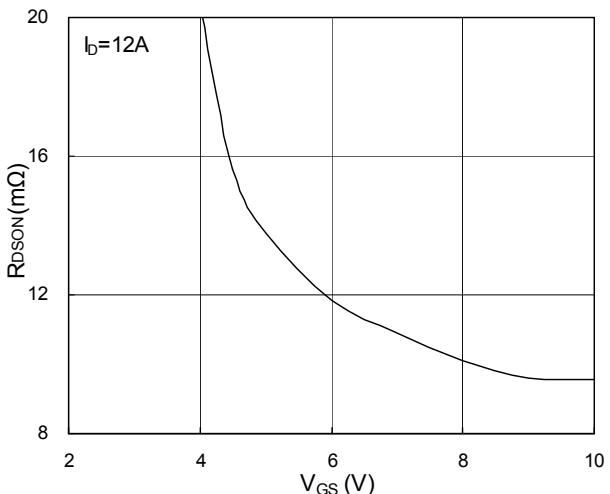


**Fig.3 Forward Characteristics of Reverse**

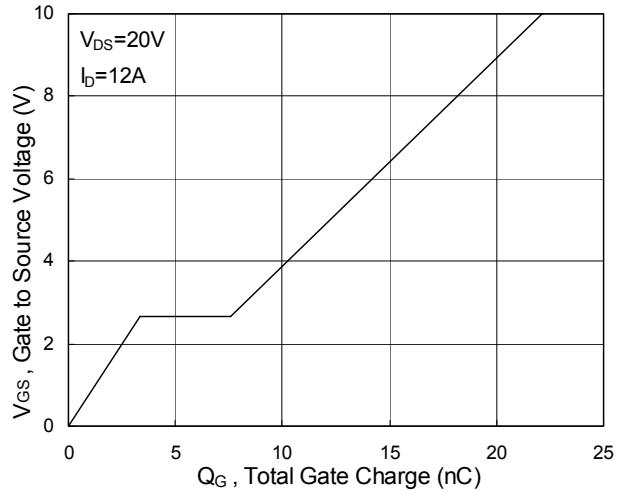


**Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$**

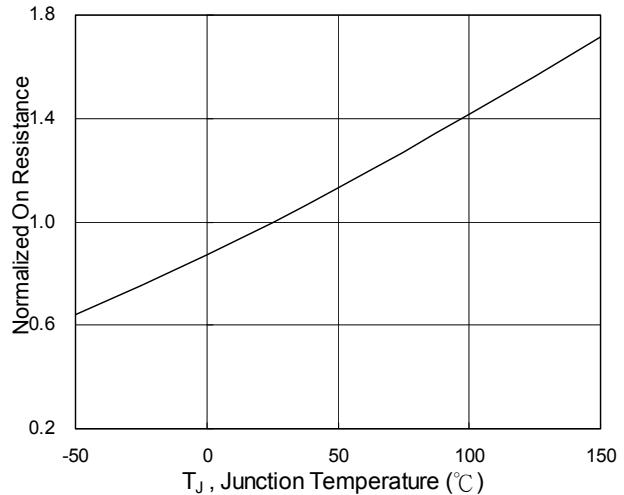
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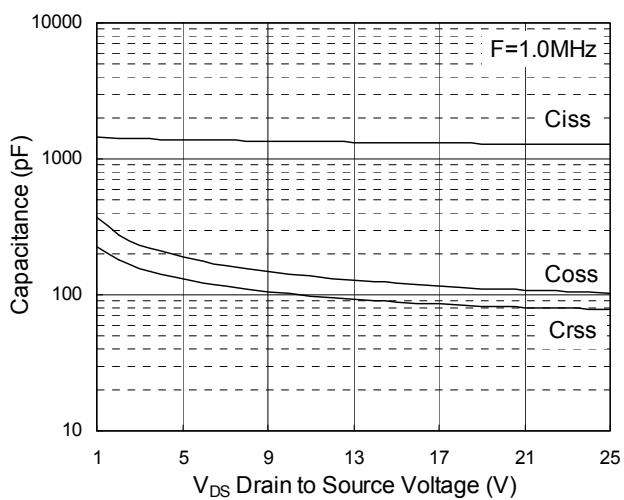
**Fig.2 On-Resistance vs. G-S Voltage**



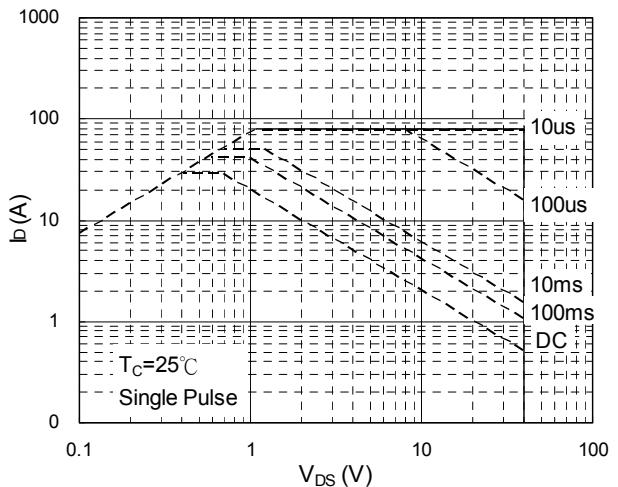
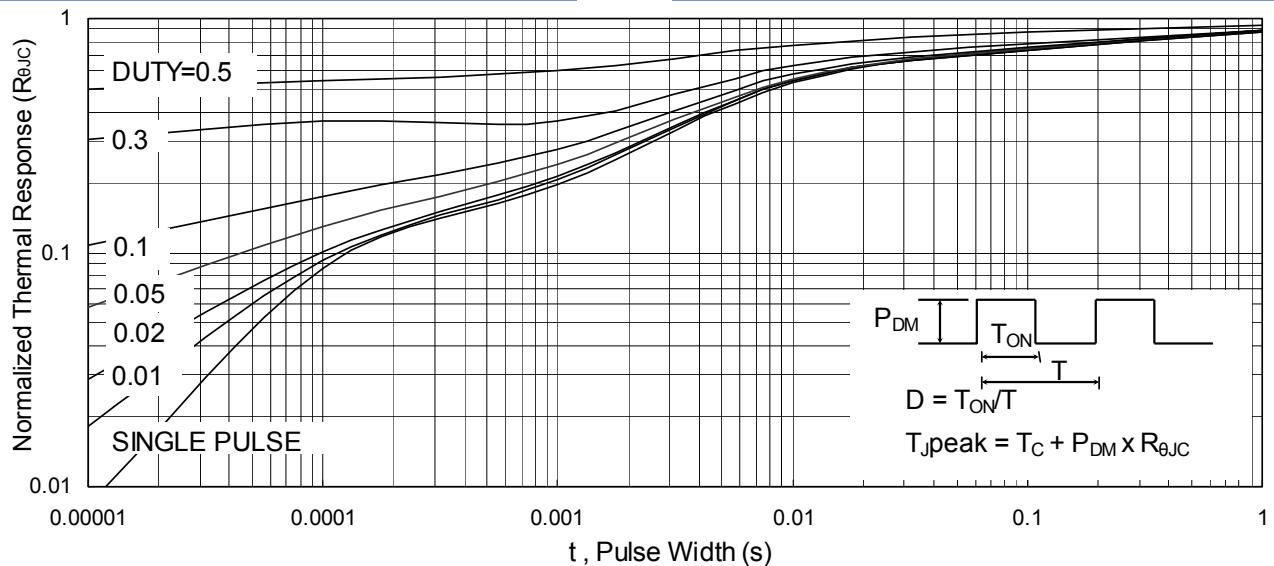
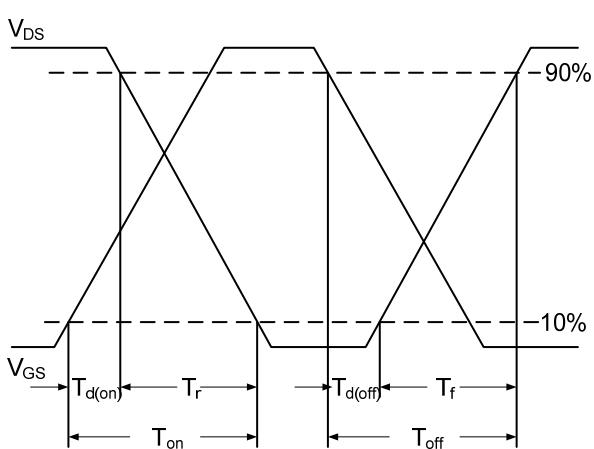
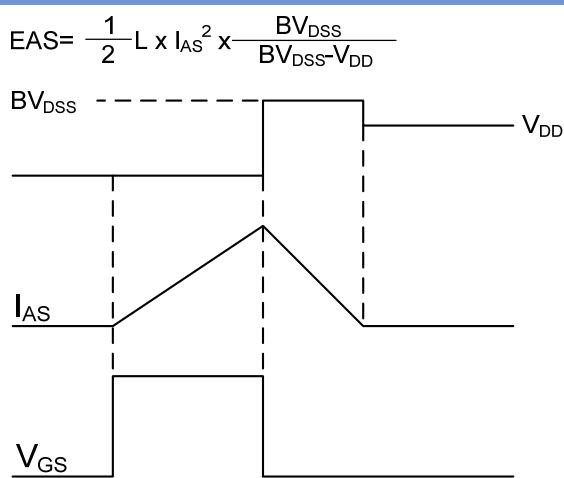
**Fig.4 Gate-Charge Characteristics**



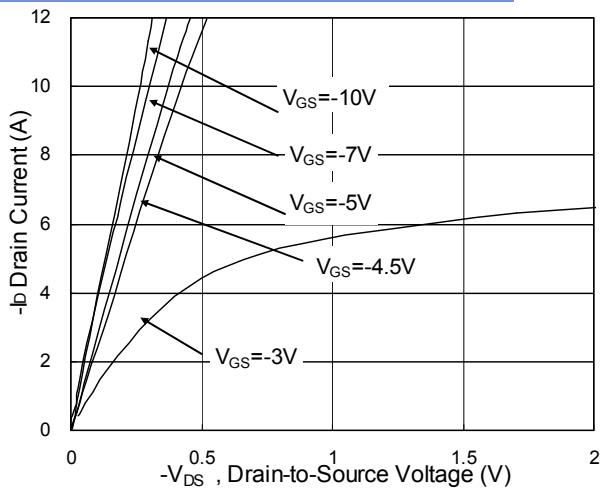
**Fig.6 Normalized  $R_{DSON}$  vs.  $T_J$**


**Fig.7 Capacitance**

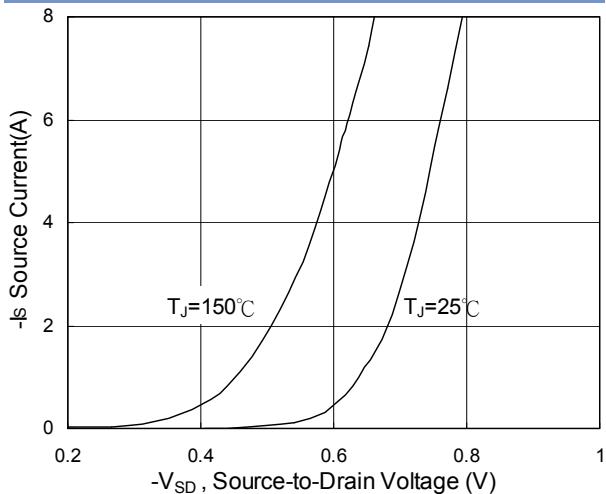
### N-Ch and P-Ch Fast Switching MOSFETs


**Fig.8 Safe Operating Area**

**Fig.9 Normalized Maximum Transient Thermal Impedance**

**Fig.10 Switching Time Waveform**

**Fig.11 Unclamped Inductive Switching Wave**

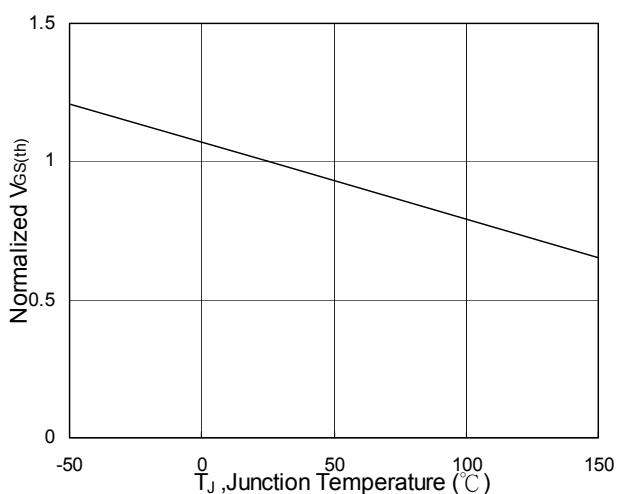
**P-Channel Typical Characteristics**



**Fig.1 Typical Output Characteristics**

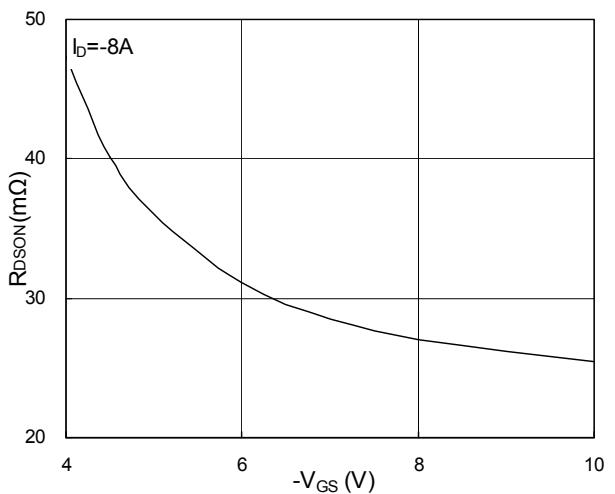


**Fig.3 Forward Characteristics of Reverse**

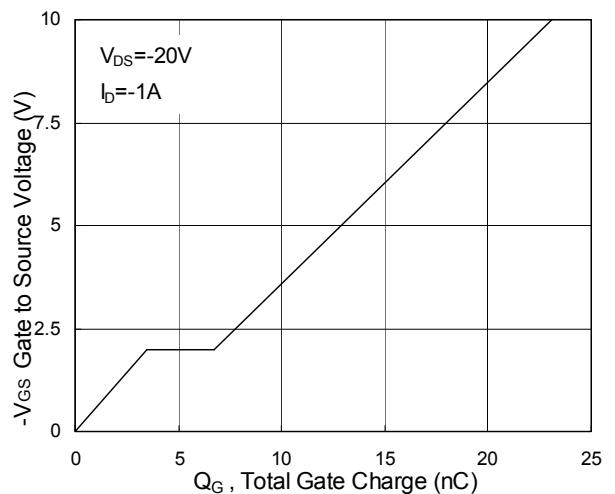


**Fig.5 Normalized  $V_{GS(th)}$  v.s  $T_J$**

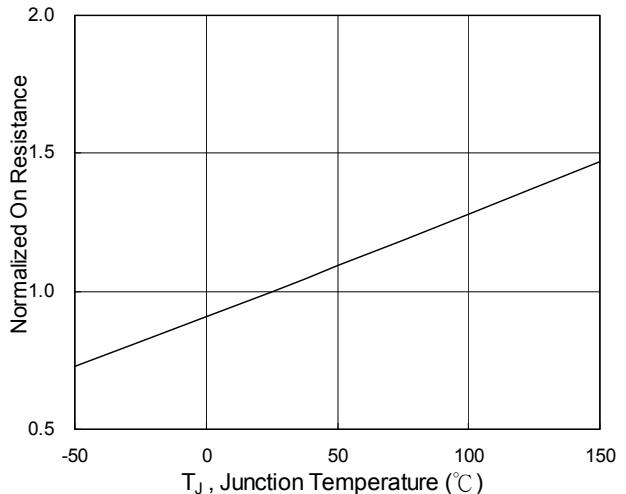
**N-Ch and P-Ch Fast Switching MOSFETs**



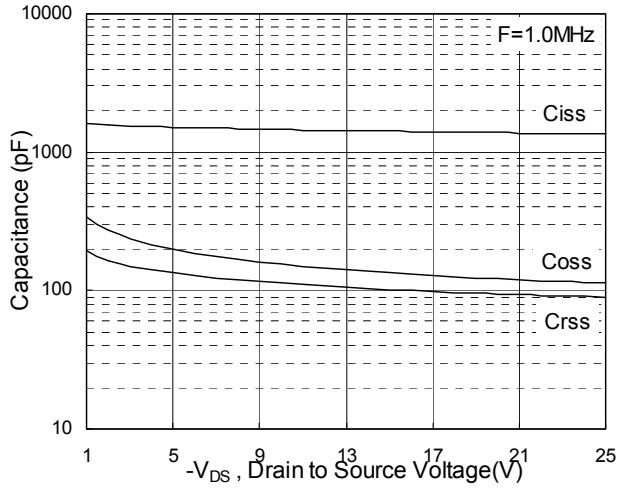
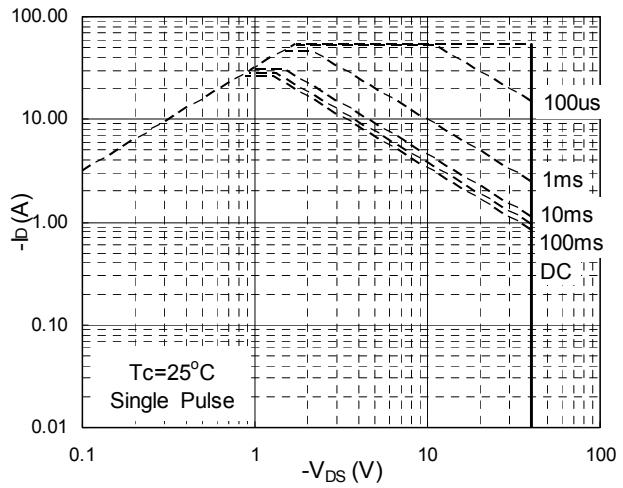
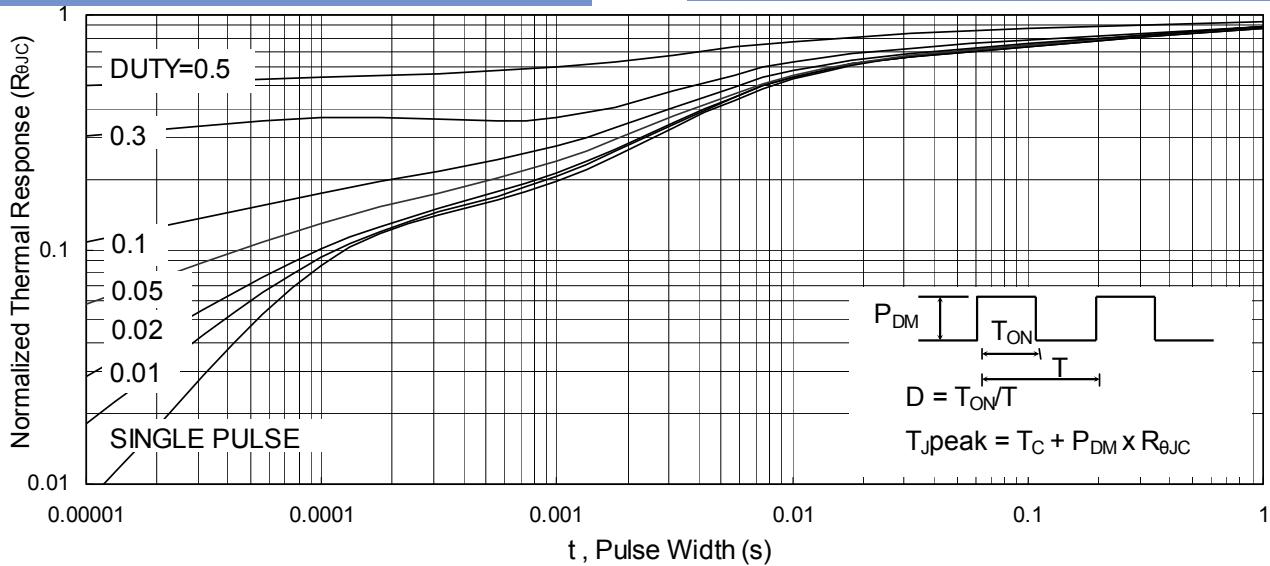
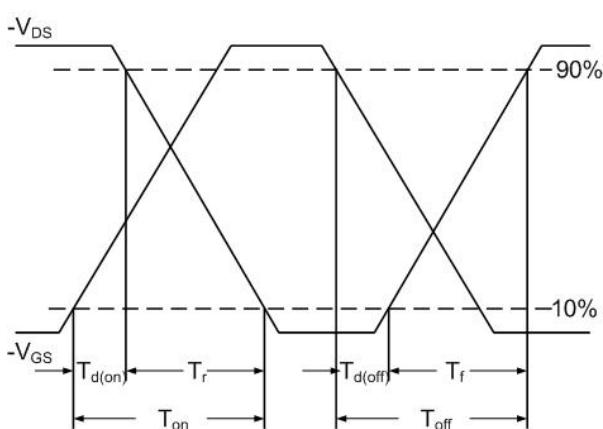
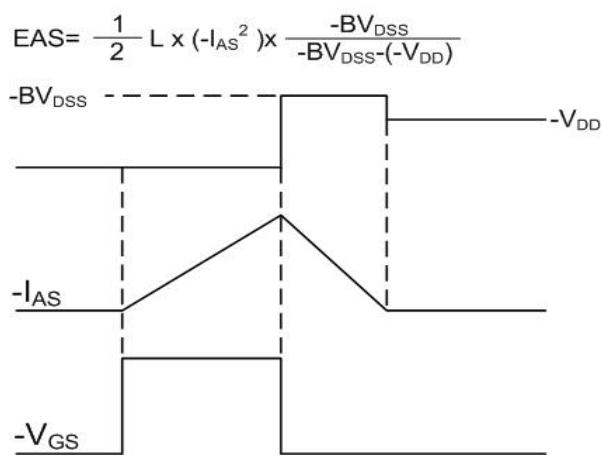
**Fig.2 On-Resistance v.s Gate-Source**



**Fig.4 Gate-Charge Characteristics**



**Fig.6 Normalized  $R_{DS(on)}$  v.s  $T_J$**

**N-Ch and P-Ch Fast Switching MOSFETs**

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